

December 2008

FOD852

4-Pin High Operating Temperature Photodarlington Optocoupler

Features

- Applicable to Pb-free IR reflow soldering
- Compact 4-pin package
- High current transfer ratio: 1000% minimum
- C-UL, UL, and VDE approved
- High input-output isolation voltage of 5000Vrms
- High operating temperature of 100°C

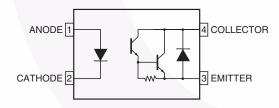
Applications

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs

Description

The FOD852 consists of gallium arsenide infrared emitting diode driving a silicon photodarlington output (with integral base-emitter resistor) in a 4-pin dual in-line package.

Functional Block Diagram





Absolute Maximum Ratings ($T_A = 25^{\circ}C$ Unless otherwise specified.) Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Units	
TOTAL DEVIC	E			
T _{STG}	Storage Temperature	-55 to +125	°C	
T _{OPR}	Operating Temperature	-30 to +100	°C	
T _{SOL}	Lead Solder Temperature	260 for 10 sec	°C	
P _{TOT}	Total Device Power Dissipation	200	mW	
INPUT				
I _F	Continuous Forward Current	50	mA	
V _R	Reverse Voltage	6	V	
P _D	LED Power Dissipation	70	mW	
OUTPUT		·		
V _{CEO}	Collector-Emitter Voltage	300	V	
V _{ECO}	Emitter-Collector Voltage	0.1	V	
I _C	Continuous Collector Current	150	mA	
P _C	Collector Power Dissipation	150	mW	

Electrical Characteristics (T_A = 25°C unless otherwise specified.)

Individual Component Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
INPUT			•			
V _F	Forward Voltage	I _F = 10mA		1.2	1.4	V
I _R	Reverse Current	$V_R = 4V$			10	μA
Ct	Terminal Capacitance	V = 0, f = 1kHz		30	250	pF
OUTPUT			•			
I _{CEO}	Collector Dark Current	V _{CE} = 200V, I _F = 0			200	nA
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 0.1 \text{mA}, I_F = 0$	300			V
BV _{ECO}	Emitter-Collector Breakdown Voltage	$I_E = 10\mu A, I_F = 0$	0.1			V

Transfer Characteristics

Symbol	DC Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
I _C	Collector Current	$I_F = 1 \text{mA}, V_{CE} = 2 \text{V}$	10	40	1 f0	mA
CTR	Current Transfer Ratio ⁽¹⁾		1,000	4,000	15,000	%
V _{CE (sat)}	Collector-Emitter Saturation Voltage	$I_F = 20 \text{mA}, I_C = 100 \text{mA}$			1.2	V
R _{iso}	Isolation Resistance	DC500V 40~60% R.H.	5x10 ¹⁰	1x10 ¹¹		Ω
C _f	Floating Capacitance	V = 0, f = 1MHz		0.6	1	pF
f _C	Cut-Off Frequency	$V_{CE} = 2V, I_{C} = 20mA, R_{L} = 100\Omega, -3dB$	1	7		kHz
t _r	Response Time (Rise)	$V_{CE} = 2V, I_{C} = 20mA, R_{L} = 100\Omega$		100	300	μs
t _f	Response Time (Fall)			20	100	μs

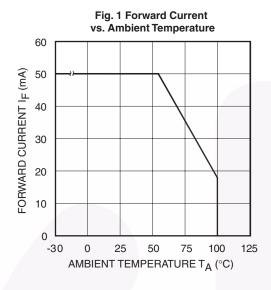
Isolation Characteristics

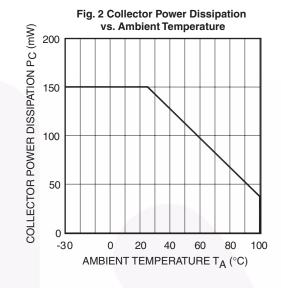
Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Units
V _{ISO}	Input-Output Isolation Voltage	$f = 60Hz, t = 1 min, I_{I-O} \le 2\mu A$	5000			Vac(rms)
R _{ISO}	Isolation Resistance	V _{I-O} = 500 VDC	5 x 10 ¹⁰	10 ¹¹	_	Ω
C _{ISO}	Isolation Capacitance	V _{I-O} = 0, f = 1MHz		0.6	1.0	pf

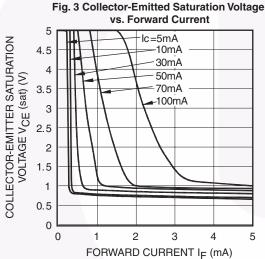
Note:

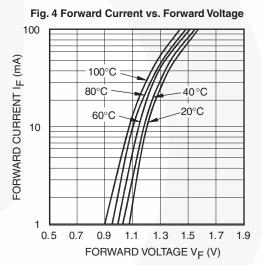
1. Current Transfer Ratio (CTR) = $I_C/I_F x 100\%$.

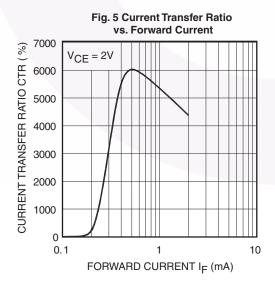
Typical Electrical/Optical Characteristic Curves (T_A = 25°C Unless otherwise specified.)

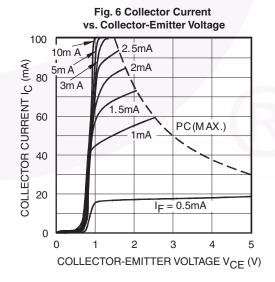






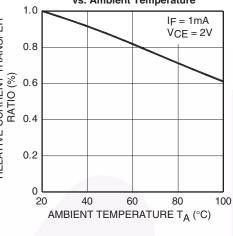


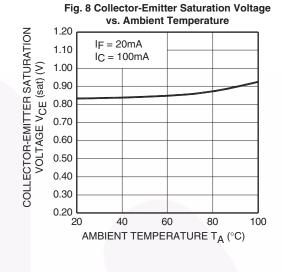


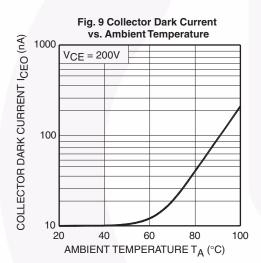


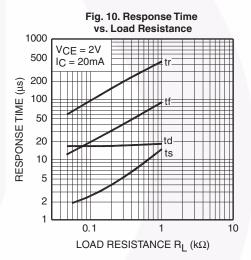
Typical Electrical/Optical Characteristic Curves (T_A = 25°C Unless otherwise specified.)

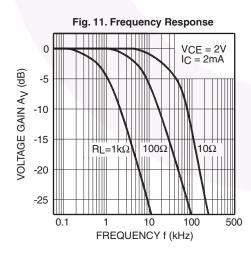
Fig. 7. Relative Current Transfer Ratio vs. Ambient Temperature IF = 1mARELATIVE CURRENT TRANSFER VCE = 2V 0.8 RATIO (%) 0.6 0.4 0.2 0 40 60 80

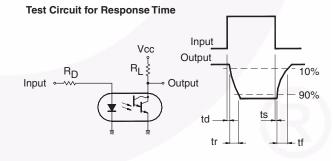


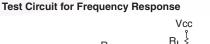










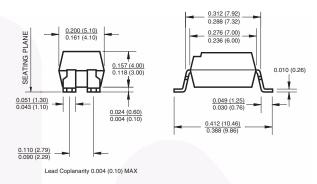


Package Dimensions

Through Hole

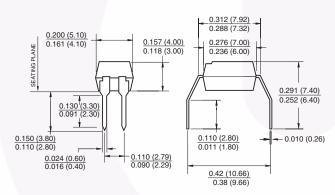
0.312 (7.92) 0.288 (7.32) 0.288 (7.32) 0.276 (7.00) 0.161 (4.10) 0.157 (4.00) 0.118 (3.00) 0.091 (2.30) 0.010 (0.26) 0.010 (0.26) 0.010 (0.26) 0.010 (0.26) 0.010 (0.26)

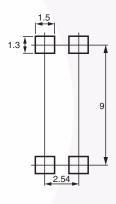
Surface Mount



Surface Mount (Footprint Dimensions)

0.4" Lead Spacing





Note:

All dimensions are in inches (millimeters)

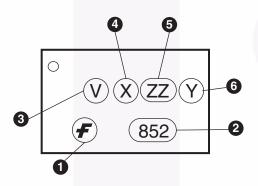
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Ordering Information

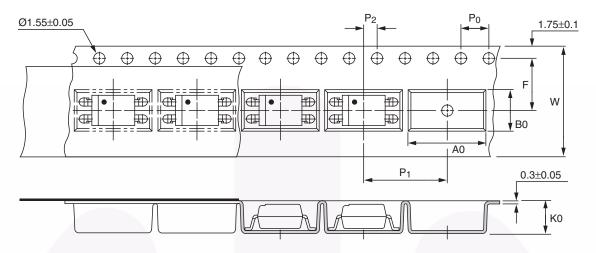
Option	Order Entry Identifier	Description
S	.S	Surface Mount Lead Bend
SD	.SD	Surface Mount; Tape and reel
W	.W	0.4" Lead Spacing
300	.300	VDE Approved
300W	.300W	VDE Approved, 0.4" Lead Spacing
3S	.3S	VDE Approved, Surface Mount
3SD	.3SD	VDE Approved, Surface Mount, Tape & Reel

Marking Information



Definiti	ons
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Carrier Tape Specifications

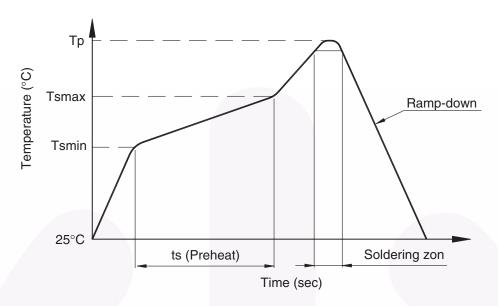


Note:

All dimensions are in millimeters.

Symbol	Description	Dimensions in mm (inches)
W	Tape wide	16 ± 0.3 (.63)
P ₀	Pitch of sprocket holes	4 ± 0.1 (.15)
F P ₂	Distance of compartment	7.5 ± 0.1 (.295) 2 ± 0.1 (.079)
P ₁	Distance of compartment to compartment	12 ± 0.1 (.472)
A0	Compartment	10.45 ± 0.1 (.411)
В0		5.30 ± 0.1 (.209)
K0		4.25 ± 0.1 (.167)

Lead Free Recommended IR Reflow Condition



Profile Feature	Pb-Sn solder assembly	Lead Free assembly
Preheat condition (Tsmin-Tsmax / ts)	100°C ~ 150°C 60 ~ 120 sec	150°C ~ 200°C 60 ~120 sec
Melt soldering zone	183°C 60 ~ 120 sec	217°C 30 ~ 90 sec
Peak temperature (Tp)	240 +0/-5°C	260 +0/-5°C
Ramp-down rate	6°C/sec max.	6°C/sec max.

Recommended Wave Soldering condition

Profile Feature	For all solder assembly
Peak temperature (Tp)	Max 260°C for 10 sec





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Definition of Terms				
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Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
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